MMIC REFLECTIONLESS FILTERS

 50Ω DC to 21 GHz

The Big Deal

- Patented design eliminates in band spurs
- Pass band cut-off up to 21 GHz
- Stop band up to 35 GHz
- Excellent repeatability through IPD* process



Product Overview

Mini-Circuits' *X-Series* reflectionless filters employs a novel filter topology which absorbs and terminates stop band signals internally rather than reflecting them back to the source. This new capability enables unique applications for filter circuits beyond those suited to traditional approaches. Traditional filters are reflective in the stop band, sending signals back to the source at 100% of the power level which interact with neighboring components and often result in intermodulation and other interferences. Reflectionless filters eliminate stop band reflections, allowing them to be paired with sensitive devices and used in applications that otherwise require circuits such as isolation amplifiers or attenuators.

Key Features	Advantages
Easy integration with sensitive reflective components, e.g. mixers, multipliers	Reflectionless filters absorb unwanted signals, preventing reflections back to the source. This reduces generation of additional unwanted signals without the need for extra components like attenuators, improving system dynamic range and saving board space.
Enables stable integration of wideband amplifiers	Because reflectionless filters maintain good impedance in the stop band; they can be integrated with high gain, wideband amplifiers without the risk of creating instabilities in these out of band regions.
Cascadable	Reflectionless filters can be cascaded in multiple sections to provide sharper and higher attenuation, while also preventing any standing waves that could affect pass band signals.
Excellent power handling in a tiny surface mount device	High power handling extends the usability of these filters to the transmit path for inter-stage filtering.
Small size, 3x3mm QFN	Allows replacement of filter/attenuator pairs with a single reflectionless filter, saving board space.
Excellent repeatability of RF performance	Through semiconductor IPD process, X-series filters are inherently repeatable for large volume production.
Excellent stability over temperature	With ±0.3 dB variation over temperature ideal for use in wide temperature range applications without the need for additional temperature compensation.
Operating temperature up to 105°C	Suitable for operation close to high power components.

^{*}IPD - Integrated Passive Device, is a GaAs semiconductor process



Reflectionless Low Pass Filter

XLF-123+

50 Ω DC to 12200 MHz

Features

- Match to 50Ω in the stop band, eliminates undesired reflections
- Cascadable
- Excellent Power handling
- Temperature stable, up to 105°C
- Small size, 3 x 3 mm
- Protected by US Patent No. 8,392,495

Applications

- Harmonics Rejection
- Satellite
- Radar
- Military & Space



CASE STYLE: DQ1225

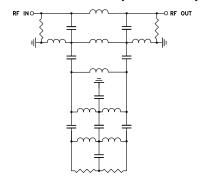
+RoHS Compliant
The +Suffix identifies RoHS Compliance. See our web site for RoHS Compliance methodologies and qualifications

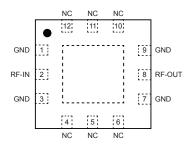


General Description

Mini-Circuits' XLF-123+ reflectionless filter employs a novel filter topology which absorbs and terminates stop band signals internally rather than reflecting them back to the source. This new capability enables unique applications for filter circuits beyond those suited to traditional approaches. Traditional filters are reflective in the stop band, sending signals back to the source at 100% of the power level. These reflections interact with neighboring components and often result in inter-modulation and other interferences. Reflectionless filters eliminate stop band reflections, allowing them to be paired with sensitive devices and used in applications that otherwise require circuits such as isolation amplifiers or attenuators.

simplified schematic and pad description





Function	Pad Number	Description
RF-IN	2	RF Input Pad
RF-OUT	8	RF Output Pad
GND	1,3,7,9, Paddle	Connected to ground
NC (GND Externally)	4,5,6,10,11,12	No internal connection

Electrical Specifications¹ at 25°C

Parameter		F#	Frequency (MHz)	Min.	Тур.	Max.	Unit
	Insertion Loss	DC - F1	DC-12200	_	1.8	2.4	dB
Pass Band	Frequency Cut-off	F2	15000	_	3.0	_	dB
	VSWR	DC - F1	DC-12200	_	1.3	_	:1
		F3 - F4	18100 - 19000	14	16	_	dB
	Rejection	F4 - F5	19000 - 29000	18	20	_	dB
Stop Band							
	VSWR	F3 - F4	18100 - 19000	_	1.3	_	:1
		F4 - F5	19000 - 29000	_	2.5	_	:1

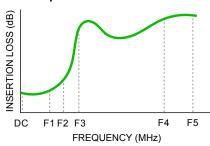
¹ Measured on Mini-Circuits Characterization Test Board TB-844-123+

Absolute Maximum Ratings⁴

Parameter	Ratings
Operating Temperature	-55°C to +105°C
Storage Temperature	-65°C to +150°C
RF Power Input, Passband (DC-F1) ²	2W at 25°C
RF Power Input, Stopband (F2-F5)3	50mW at 25°C

 $^{^{\}rm 2}$ Passband rating derates linearly to 1W at 105°C ambient

Specification Definition



ESD rating

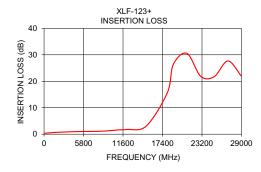
Human body model (HBM): Class 1A (250 to <500V) in accordance with ANSI/ESD 5.1-2001

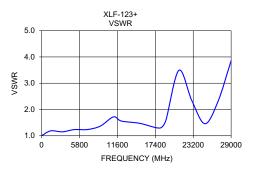
MSL rating

Moisture Sensitivity: MSL1 in accordance with IPC/JEDEC J-STD-020D

Typical Performance Data at 25°C

Frequency (MHz)	Insertion Loss (dB)	VSWR (:1)	
10	0.39	1.01	_
100	0.35	1.02	
200	0.37	1.04	
400	0.42	1.06	
800	0.50	1.13	
1600	0.66	1.19	
3200	0.83	1.15	
5000	0.99	1.24	
7000	1.05	1.24	
9000	1.19	1.37	
11000	1.63	1.72	
12200	1.79	1.56	
15000	3.04	1.47	
18100	15.60	1.29	
19000	26.46	1.57	
21000	30.52	3.49	
23000	21.89	2.33	
25000	21.74	1.46	
27000	27.66	2.31	
29000	21.90	3.86	



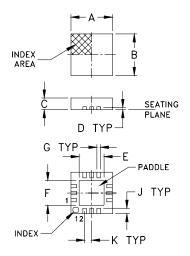


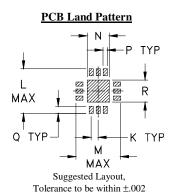


Stopband rating derates linearly to 25mW at 105°C ambient
 Permanent damage may occur if any of these limits are exceeded.

XLF-123+

Outline Drawing

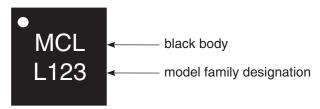




Outline Dimensions (inch)

J	Н	G	F	E	D	С	В	Α
.016		.009	.057	.057	.008	.035	.118	.118
0.41		0.23	1.45	1.45	0.20	0.89	3.00	3.00
wt		R	Q	Р	N	M	L	K
wt grams	,				N .049			

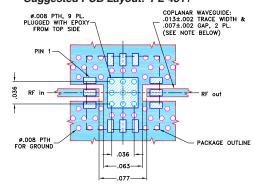
Product Marking



Demo Board MCL P/N:

TB-844-123+ (without connectors) TB-844-123C+ (with connectors)

B20-118-F1+ Connector sold separately Suggested PCB Layout: PL-451+

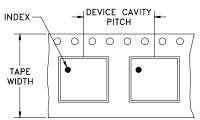


- NOTES:

 1. TRACE WIDTH PARAMETERS ARE SHOWN FOR ROGERS R04350B WITH DIELECTRIC THICKNESS .0066"±.0007". COPPER: 1/2 0Z. EACH SIDE. FOR OTHER MATERIALS TRACE WIDTH AND GAP MAY NEED TO BE MODIFIED. 2. BOTTOM SIDE OF THE PCB IS CONTINUOUS GROUND PLANE.
- DENOTES PCB COPPER LAYOUT WITH SMOBC (SOLDER MASK OVER BARE COPPER). DENOTES COPPER LAND PATTERN FREE OF SOLDER MASK.

Tape & Reel Packaging

DEVICE ORIENTATION IN T&R



DIRECTION OF FEED

Tape Width, mm	Device Cavity Pitch, mm	Reel Size, inches	Devices per Reel see note		
8	4	7	Small quantity standard	20 50 100 200 500	
		7	Standard	1000, 2000	